



Material Content Data Sheet



Sales Product Name		BSL306N H6327		Issued		2. August 2018		
MA#		MA001190008						
Package		PG-TSOP6-6-4		Weight*		14.84 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	non noble metal	tin	7440-31-5	0.009	0.06		595	
	noble metal	gold	7440-57-5	0.034	0.23		2306	
	inorganic material	silicon	7440-21-3	0.522	3.52	3.81	35174	38075
leadframe	inorganic material	silicon	7440-21-3	0.001	0.01		95	
	non noble metal	titanium	7440-32-6	0.007	0.05		477	
	non noble metal	chromium	7440-47-3	0.021	0.14		1431	
	non noble metal	copper	7440-50-8	7.048	47.50	47.70	474964	476967
wire	non noble metal	copper	7440-50-8	0.049	0.33	0.33	3275	3275
encapsulation	organic material	carbon black	1333-86-4	0.066	0.45		4452	
	plastics	epoxy resin	-	1.420	9.57		95721	
	inorganic material	silicondioxide	60676-86-0	5.120	34.50	44.52	345042	445215
leadfinish	non noble metal	tin	7440-31-5	0.392	2.64	2.64	26450	26450
plating	noble metal	silver	7440-22-4	0.149	1.00	1.00	10018	10018
*deviation	< 10%		Sum in total:			100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and does not use any exemption

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